Vishay Siliconix

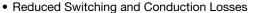
E Series Power MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	650				
R _{DS(on)} max. at 25 °C (Ω)	V _{GS} = 10 V 0.18				
Q _g max. (nC)	86				
Q _{gs} (nC)	14				
Q _{gd} (nC)	26				
Configuration	Single				

TO-247AC G N-Channel MOSFET

FEATURES

- Low Figure-of-Merit (FOM) Ron x Qq
- Low Input Capacitance (C_{iss})



- Ultra Low Gate Charge (Q_a)
- Avalanche Energy Rated (UIS)
- Material categorization: For definitions please see <u>www.vishay.com/doc?99912</u>



APPLICATIONS

- Server and Telecom Power Supplies
- Switch Mode Power Supplies (SMPS)
- Power Factor Correction Power Supplies (PFC)
- Lighting
 - High-Intensity Discharge (HID)
 - Fluorescent Ballast Lighting
- Industrial
 - Welding
 - Induction Heating
 - Motor Drives
 - Battery Chargers
 - Renewable Energy
 - Solar (PV Inverters)

ORDERING INFORMATION				
Package	TO-247AC			
Lead (Pb)-free	SiHG22N60E-E3			
Lead (Pb)-free and Halogen-free	SiHG22N60E-GE3			

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-Source Voltage			V _{DS}	600		
Gate-Source Voltage			.,	± 20	V	
Gate-Source Voltage AC (f > 1 Hz)			V_{GS}	30		
Continuous Proin Current (T = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	- I _D	21	А	
Continuous Drain Current (T _J = 150 °C)	V _{GS} at 10 V	T _C = 100 °C		13		
Pulsed Drain Current ^a			I _{DM}	56		
Linear Derating Factor				1.8	W/°C	
Single Pulse Avalanche Energy ^b			E _{AS}	367	mJ	
Maximum Power Dissipation			P_{D}	227	W	
Operating Junction and Storage Temperature Range			T _J , T _{stg}	- 55 to + 150	°C	
Drain-Source Voltage Slope T _J = 125 °C		dV/dt	37	V/ns		
Reverse Diode dV/dt ^d			11	V/IIS		
Soldering Recommendations (Peak Temperature) for 10 s				300°	°C	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature.
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 5.1 A.
- c. 1.6 mm from case.
- d. $I_{SD} \le I_D$, dI/dt = 100 A/ μ s, starting $T_J = 25$ °C.



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum Junction-to-Ambient	R _{thJA}	-	62	°C/W	
Maximum Junction-to-Case (Drain)	R_{thJC}	-	0.55	C/VV	

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static						•	
Drain-Source Breakdown Voltage	V_{DS}	V _{GS} :	= 0 V, I _D = 250 μA	600	-	-	V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = 250 μA	-	0.71	-	V/°C
Gate-Source Threshold Voltage (N)	V _{GS(th)}	V _{DS} =	= V _{GS} , I _D = 250 μA	2	-	4	V
Gate-Source Leakage	I _{GSS}		V _{GS} = ± 20 V	-	-	± 100	nA
		V _{DS} =	V _{DS} = 600 V, V _{GS} = 0 V		-	1	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 480 \	/, V _{GS} = 0 V, T _J = 125 °C	-	-	10	μA
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V		-	0.15	0.18	Ω
Forward Transconductance	9 _{fs}	V _D	_S = 8 V, I _D = 5 A	-	6.4	-	S
Dynamic			-	l	l		
Input Capacitance	C _{iss}		V _{GS} = 0 V,	-	1920	-	
Output Capacitance	C _{oss}	1	$V_{DS} = 100 \text{ V},$	-	90	-	-
Reverse Transfer Capacitance	C _{rss}		f = 1 MHz	-	6	-	
Effective Output Capacitance, Energy Related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	73	-	pF
Effective Output Capacitance, Time Related ^b	C _{o(tr)}			-	263	-	
Total Gate Charge	Qg			-	57	86	
Gate-Source Charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_{D} = 11 \text{ A}, V_{DS} = 480 \text{ V}$		14	-	nC
Gate-Drain Charge	Q _{gd}			-	26	-	
Turn-On Delay Time	t _{d(on)}	$V_{DD} = 380 \text{ V}, I_{D} = 11 \text{ A}, \ V_{GS} = 10 \text{ V}, R_{g} = 4.7 \Omega$		-	18	36	
Rise Time	t _r			-	68	105	ns
Turn-Off Delay Time	$t_{d(off)}$			-	59	89	
Fall Time	t _f			-	54	81	
Gate Input Resistance	R_g	f = 1 MHz, open drain		-	0.77	-	Ω
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21	
Pulsed Diode Forward Current	I _{SM}			-	-	88	- A
Diode Forward Voltage	V _{SD}	T _J = 25 °C, I _S = 11 A, V _{GS} = 0 V		-	-	1.2	V
Reverse Recovery Time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 11 \text{ A},$ $dI/dt = 100 \text{ A/µs}, V_R = 20 \text{ V}$		-	460	-	ns
Reverse Recovery Charge	Q _{rr}			-	7.3	-	μC
Reverse Recovery Current	I _{RRM}			_	26	_	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} . b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} .



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

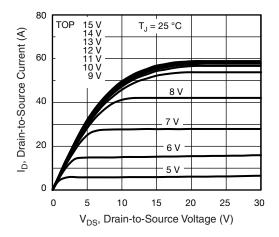


Fig. 1 - Typical Output Characteristics

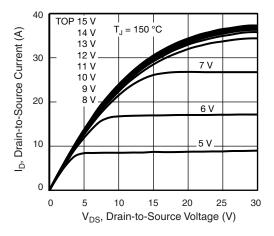


Fig. 2 - Typical Output Characteristics

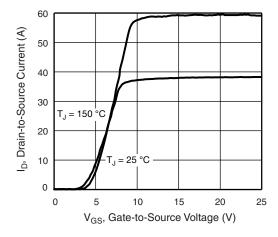


Fig. 3 - Typical Transfer Characteristics

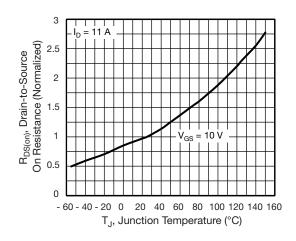


Fig. 4 - Normalized On-Resistance vs. Temperature

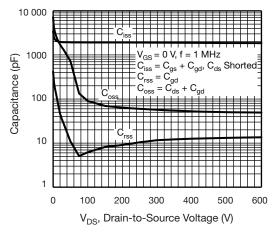


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

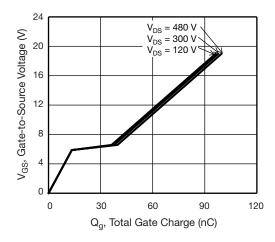


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



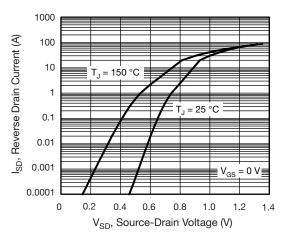


Fig. 7 - Typical Source-Drain Diode Forward Voltage

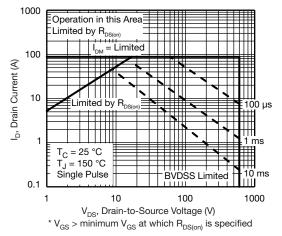


Fig. 8 - Maximum Safe Operating Area

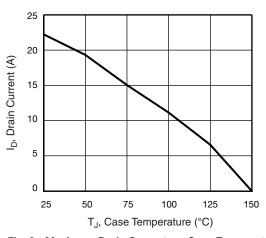


Fig. 9 - Maximum Drain Current vs. Case Temperature

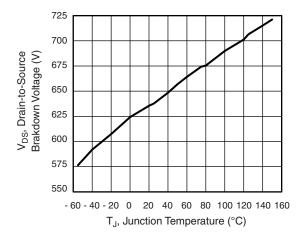


Fig. 10 - Temperature vs. Drain-to-Source Voltage

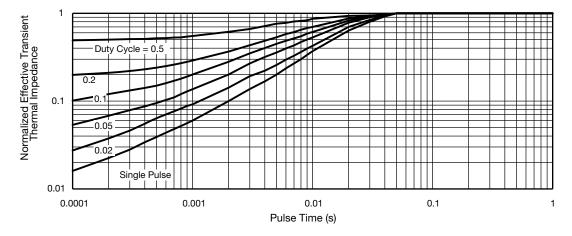


Fig. 11 - Normalized Thermal Transient Impedance, Junction-to-Case



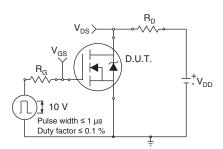


Fig. 12 - Switching Time Test Circuit

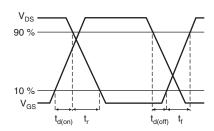


Fig. 13 - Switching Time Waveforms

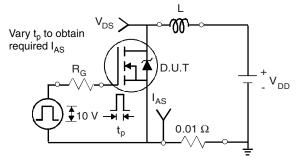


Fig. 14 - Unclamped Inductive Test Circuit

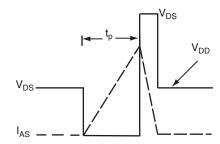


Fig. 15 - Unclamped Inductive Waveforms

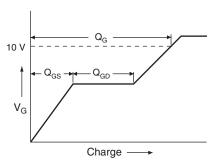


Fig. 16 - Basic Gate Charge Waveform

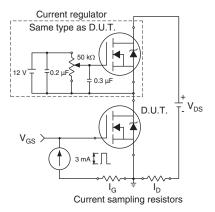
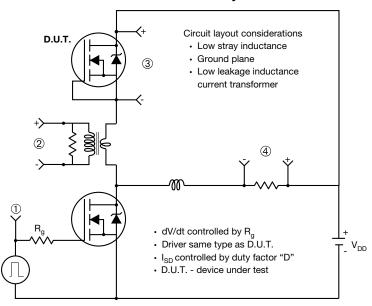


Fig. 17 - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



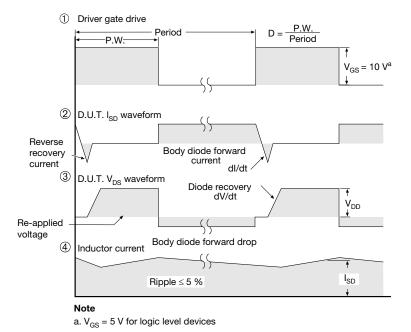


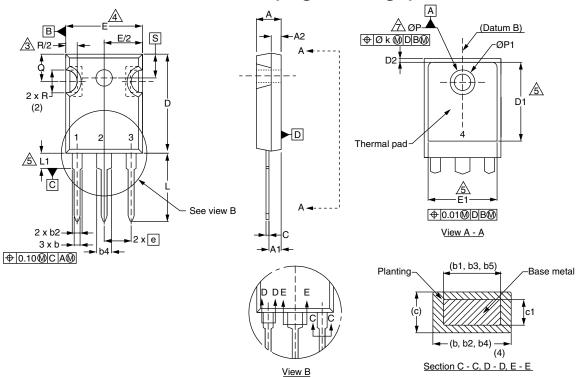
Fig. 18 - For N-Channel

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www.vishay.com

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TO-247AC (High Voltage)



	MILLIM	IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
Α	4.58	5.31	0.180	0.209
A1	2.21	2.59	0.087	0.102
A2	1.17	2.49	0.046	0.098
b	0.99	1.40	0.039	0.055
b1	0.99	1.35	0.039	0.053
b2	1.53	2.39	0.060	0.094
b3	1.65	2.37	0.065	0.093
b4	2.42	3.43	0.095	0.135
b5	2.59	3.38	0.102	0.133
С	0.38	0.86	0.015	0.034
c1	0.38	0.76	0.015	0.030
D	19.71	20.82	0.776	0.820
D1	13.08	-	0.515	-

	MILLIM	IETERS	INC	HES	
DIM.	MIN.	MAX.	MIN.	MAX.	
D2	0.51	1.30	0.020	0.051	
E	15.29	15.87	0.602	0.625	
E1	13.72	-	0.540	-	
е	5.46	BSC	0.215 BSC		
Øk	0.2	0.254		0.010	
L	14.20	16.25	0.559	0.640	
L1	3.71	4.29	0.146	0.169	
N	7.62	7.62 BSC		BSC	
ØΡ	3.51	3.66	0.138	0.144	
Ø P1	-	7.39	-	0.291	
Q	5.31	5.69	0.209	0.224	
R	4.52	5.49	0.178	0.216	
S	5.51 BSC		0.217 BSC		

ECN: X12-0167-Rev. B, 24-Sep-12

DWG: 5971

Notes

- 1. Dimensioning and tolerancing per ASME Y14.5M-1994.
- 2. Contour of slot optional.
- 3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outermost extremes of the plastic body.
- 4. Thermal pad contour optional with dimensions D1 and E1.
- 5. Lead finish uncontrolled in L1.
- 6. Ø P to have a maximum draft angle of 1.5 to the top of the part with a maximum hole diameter of 3.91 mm (0.154").
- 7. Outline conforms to JEDEC outline TO-247 with exception of dimension c.
- 8. Xian and Mingxin actually photo.



Revision: 24-Sep-12 1 Document Number: 91360



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